

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.02	100.0	1.72
Subtotal				0.02	100	1.72
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05	100.0	3.4
Subtotal				0.05	100	3.4
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.46
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	4.86
	Copper alloy	Copper (Cu)	7440-50-8	66.22	99.87	4849.69
	Subtotal			66.31	100	4856.01
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.33	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.98	15.0	364.5
	Filler	Silica fused	60676-86-0	24.55	74.0	1798.2
	Flame retardant	Metal hydroxide		2.32	7.0	170.1
Subtotal				33.18	100	2430
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.41	100.0	30
Subtotal				0.41	100	30
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	65.0	1.5
	Lead alloy	Silver (Ag)	7440-22-4	0.01	25.0	0.57
	Lead alloy	Antimony (Sb)	7440-36-0	0	10.0	0.23
Subtotal				0.03	100	2.3
Total				100	100	7323.43

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.